



Material Content Data Sheet



Sales Product Name		BTS5090-1EJA		Issued		29. August 2013		
MA#		MA001136580						
Package		PG-DSO-8-43		Weight*		84.30 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.775	2.11	2.11	21058	21058
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		111	
	non noble metal	zinc	7440-66-6	0.038	0.04		446	
	non noble metal	iron	7439-89-6	0.752	0.89		8919	
wire	non noble metal	copper	7440-50-8	30.529	36.21	37.15	362139	371615
	non noble metal	copper	7440-50-8	0.361	0.43	0.43	4278	4278
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1154
plastics	plastics	epoxy resin	-	4.476	5.31		53090	
	inorganic material	silicondioxide	60676-86-0	44.074	52.27	57.70	522818	577062
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9654	9654
plating	noble metal	silver	7440-22-4	0.726	0.86	0.86	8612	8612
glue	plastics	epoxy resin	-	0.114	0.14		1351	
	noble metal	silver	7440-22-4	0.537	0.64	0.78	6370	7721
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

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